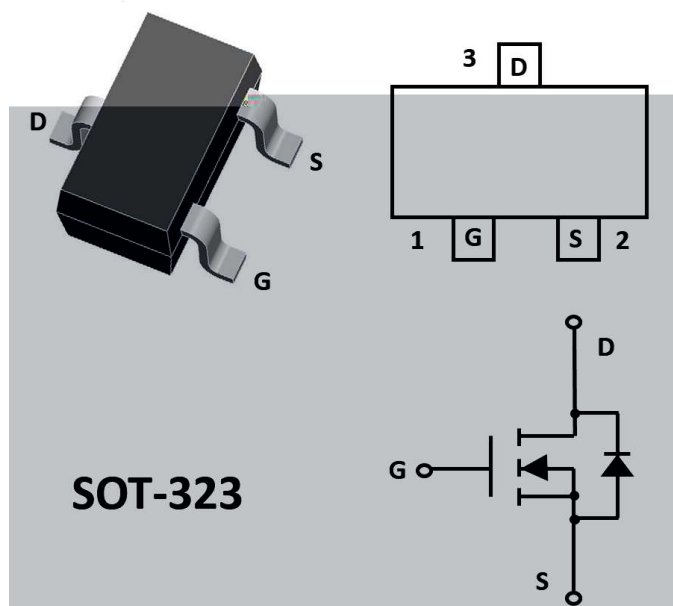


N Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} 20V
- I_D 3.0A
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) 70 mohm
- $R_{DS(ON)}$ (at $V_{GS}=2.5V$) 98 mohm

General Description

- Trench Power LV MOSFET technology
- High Power and current handling capability

Applications

- PWM application
- Load switch

■ Absolute Maximum Ratings ($T_A=25$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	20	V
Gate-source Voltage	V_{GS}	10	V
Drain Current	I_D	$T_A=25$ @ Steady State	3.0
		$T_A=70$ @ Steady State	2.4
Pulsed Drain Current ^A	I_{DM}	14	A
Total Power Dissipation @ $T_A=25$	P_D	0.25	W
Thermal Resistance Junction-to-Ambient @ Steady State ^B	$R_{\theta JA}$	500	/ W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 +150	

■ Ordering Information

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE (pcs)	INNER BOX QUANTITY (pcs)	OUTER CARTON QUANTITY (pcs)	DELIVERY MODE
YJL2102W	F2	TS2.	3000	30000	120000	7" reel

YJL2103W

($T_J=25$ unless otherwise noted)

Symbol	Conditions	Min	Typ	Max	Units	
$V_{GS(th)}$	$I_D=250\mu A$	20			V	
I_{DSS}				1	μA	
I_{S1}				100	nA	
V_{SD}					V	
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=2.5A$		57	70	m Ω
		$V_{GS}=2.5V, I_D=2.0A$		72	98	
Diode Forward Voltage	V_{SD}	$I_S=2.5A, V_{GS}=0V$			1.2	V
Maximum Body-Diode Continuous Current	I_S					
Dynamic Parameters						
Input Capacitance	C_{iss}			220		pF
Output Capacitance	C_{oss}	$V_{DS}=10V, V_{GS}=0V, f=1MHz$		34		
Reverse Transfer Capacitance	C_{rss}			26		

Typical Performance Characteristics

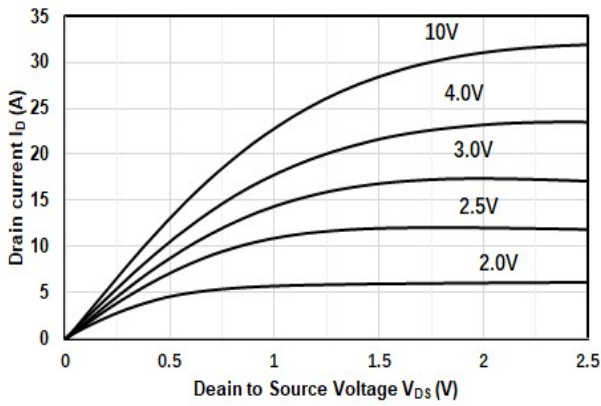


Figure1. Output Characteristics

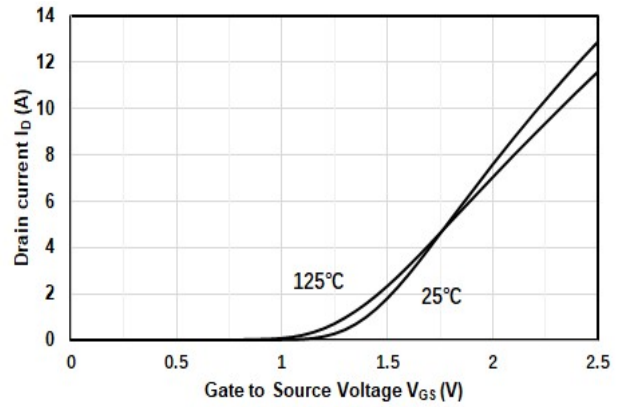


Figure2. Transfer Characteristics

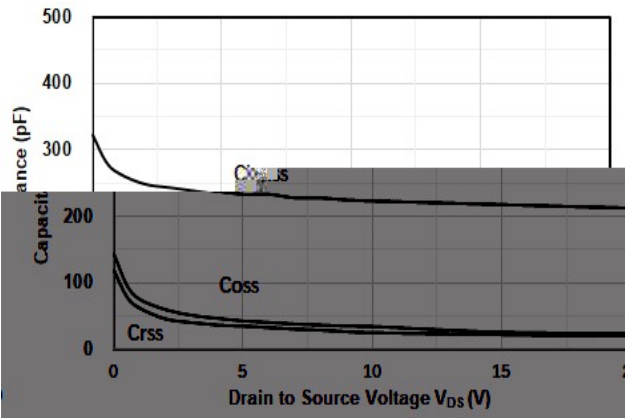


Figure3. Capacitance Characteristics

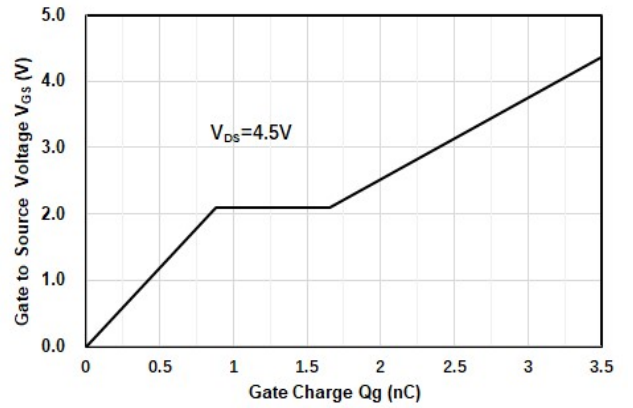


Figure4. Gate Charge

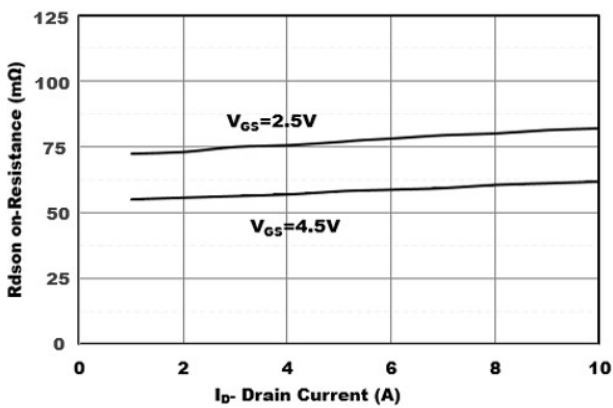


Figure5. Drain-Source on Resistance

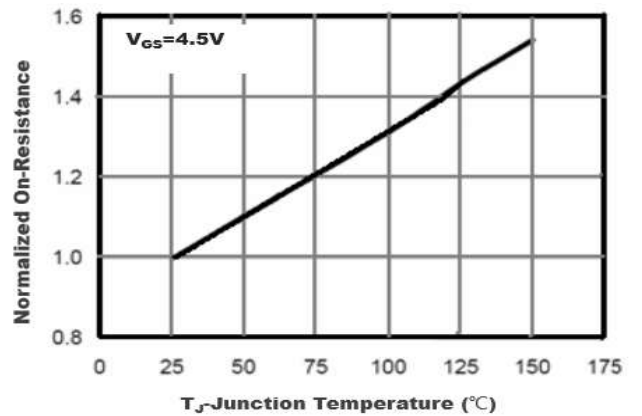


Figure6. Drain-Source on Resistance

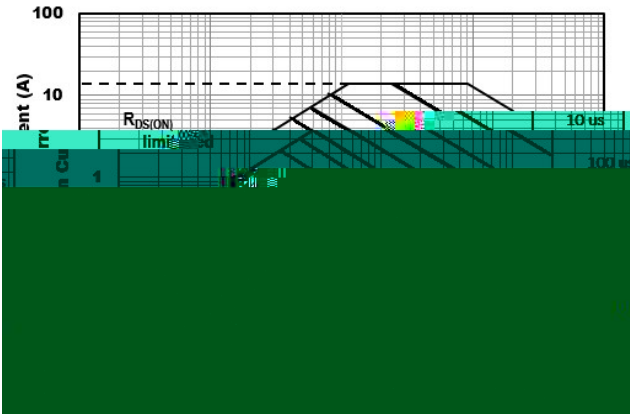


Figure7. Safe Operation Area

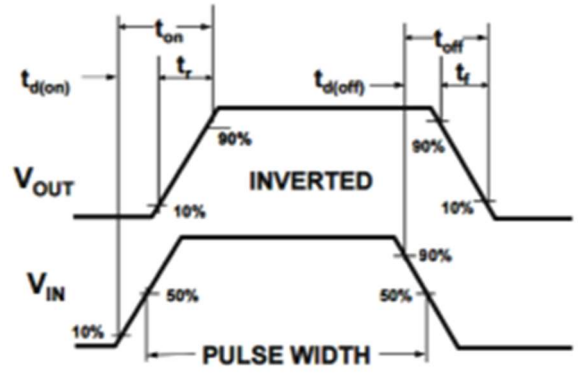
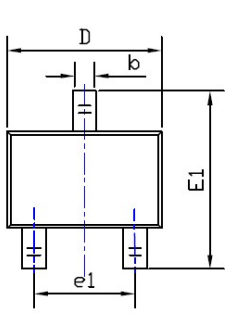
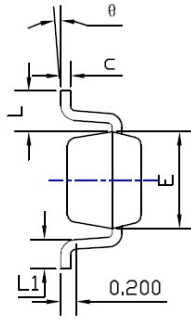


Figure8. Switching wave

■SOF-323 Package Information



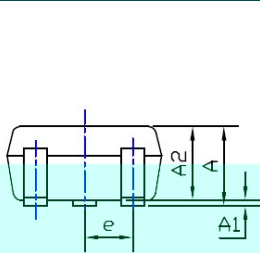
TOP VIEW



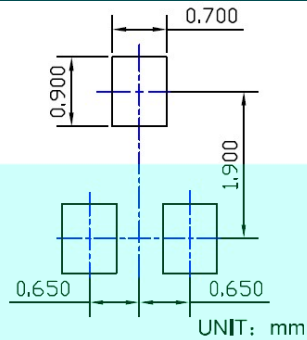
SIDE VIEW

SYMBOL	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	---	0.043	0.900	---	1.100
A1	0.000	---	0.004	0.000	---	0.100
A2	0.035	0.037	0.039	0.900	0.950	1.000
b	0.006	0.012	0.016	0.150	0.300	0.400
c	0.004	---	0.010	0.100	---	0.250
D	0.071	0.079	0.087	1.800	2.000	2.200

e	0.026TYP			0.650TYP		
e1	0.047	0.051	0.055	1.200	1.300	1.400
L	0.021REF			0.525REF		
L1	0.010	0.014	0.018	0.260	0.360	0.460
theta	0°	---	8°	0°	---	8°



SIDE VIEW



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website [http:// www.21yangjie.com](http://www.21yangjie.com) , or consult your nearest Yangjie's sales office for further assistance.